

AMENDMENT TRANSMITTAL LETTER

Docket No.
KWM-0001

Application No.
10/088,163

Filing Date
March 15, 2002

Examiner
P. Greene

Art Unit
2826

Applicant(s): Kazutaka SHIBATA

Invention: SEMICONDUCTOR DEVICE WITH CHIP-ON-CHIP CONSTRUCTION JOINED VIA A LOW-MELTING POINT METAL LAYER (AS AMENDED)

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	33	- 35 =		x	0.00
Independent Claims	4	- 6 =		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					0.00

☒ Large Entity

☐ Small Entity

☒ No additional fee is required for this amendment.

☐ Please charge Deposit Account No. _____ in the amount of \$ _____.
A duplicate copy of this sheet is enclosed.

☐ A check in the amount of \$ _____ to cover the filing fee is enclosed.

☐ Payment by credit card. Form PTO-2038 is attached.

☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. 18-0013 as described below. A duplicate copy of this sheet is enclosed.

☒ Credit any overpayment.

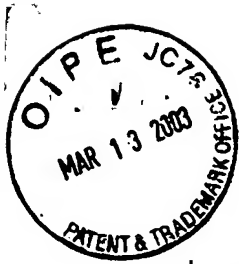
☒ Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.

Carl Schaukowitch
Carl Schaukowitch
Attorney Reg. No.: 29,211

Dated: March 13, 2003

RADER, FISHMAN & GRAUER PLLC
1233 20th Street, N.W.
Suite 501
Washington, DC 20036
(202) 955-3750
Customer No. 23353

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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Kazutaka SHIBATA

Application No.: 10/088,163

Filed: March 15, 2002

For: SEMICONDUCTOR DEVICE WITH CHIP-ON-CHIP CONSTRUCTION JOINED
VIA A LOW-MELTING POINT METAL LAYER (As Amended)

Attorney Docket No.: KWM-0001

Examiner: P. Greene

Art Unit: 2826

Confirmation No. 1108

#9/B
3/18/03

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AMENDMENT UNDER 37 C.F.R. §1.111

BOX NON-FEE AMENDMENT

Commissioner for Patents
Washington, DC 20231

Sir:

In response to the Office Action dated December 18, 2002, please amend the
above-identified application as follows:

IN THE SPECIFICATION:

Please change the title of the invention as set forth below in clean form.
Additionally, in accordance with 37 CFR 1.121(b)(1)(iii), the changed title is set forth in
a marked-up version in the page(s) attached to this Amendment.

On Page 1, before Paragraph 1:

SEMICONDUCTOR DEVICE WITH CHIP-ON-CHIP CONSTRUCTION
JOINED VIA A LOW-MELTING POINT METAL LAYER

IN THE CLAIMS:

Please cancel claims 21-24 without prejudice or disclaimer.

Please amend claims 1-6, 10, 12 and 18 as set forth below in clean form.

Additionally, in accordance with 37 CFR 1.121(c)(1)(ii), the amended claim(s) are set
forth in a marked-up version in the page(s) attached to this Amendment.

1. (Amended) A semiconductor device comprising:
a first semiconductor chip having an electrode terminal:

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